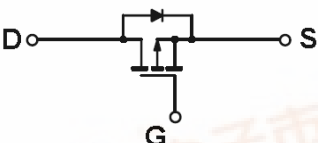


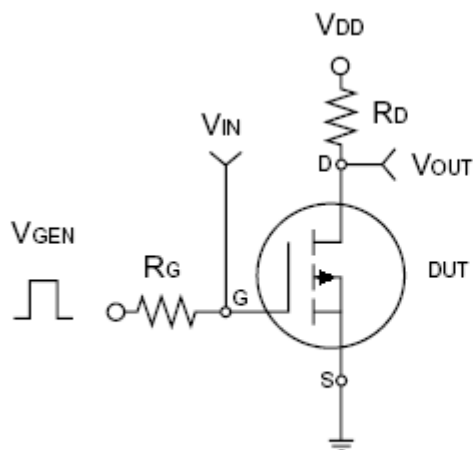
TSC 	TSM2301 20V P-Channel Enhancement Mode MOSFET																																						
SOT-23  Pin assignment: 1. Gate 2. Source 3. Drain	$V_{DS} = -20V$ $R_{DS(on)}, V_{GS} @ -4.5V, I_{ds} @ -2.8A = 130m\Omega$ $R_{DS(on)}, V_{GS} @ -2.5V, I_{ds} @ -2.0A = 190m\Omega$																																						
Features ✧ Advanced trench process technology ✧ High density cell design for ultra low on-resistance ✧ Excellent thermal and electrical capabilities ✧ Compact and low profile SOT-23 package																																							
Block Diagram 		Ordering Information <table><tr><th>Part No.</th><th>Packing</th><th>Package</th></tr><tr><td>TSM2301CX</td><td>Tape & Reel</td><td>SOT-23</td></tr></table>		Part No.	Packing	Package	TSM2301CX	Tape & Reel	SOT-23																														
Part No.	Packing	Package																																					
TSM2301CX	Tape & Reel	SOT-23																																					
Absolute Maximum Rating (Ta = 25 °C unless otherwise noted) <table><tr><th>Parameter</th><th>Symbol</th><th>Limit</th><th>Unit</th></tr><tr><td>Drain-Source Voltage</td><td>V_{DS}</td><td>- 20V</td><td>V</td></tr><tr><td>Gate-Source Voltage</td><td>V_{GS}</td><td>± 8</td><td>V</td></tr><tr><td>Continuous Drain Current</td><td>I_D</td><td>- 2.3</td><td>A</td></tr><tr><td>Pulsed Drain Current</td><td>I_{DM}</td><td>- 10</td><td>A</td></tr><tr><td rowspan="2">Maximum Power Dissipation</td><td>Ta = 25 °C</td><td>P_D</td><td>1.25</td><td rowspan="2">W</td></tr><tr><td>Ta = 75 °C</td><td></td><td>0.8</td></tr><tr><td>Operating Junction Temperature</td><td>T_J</td><td>+150</td><td>°C</td></tr><tr><td>Operating Junction and Storage Temperature Range</td><td>T_J, T_{STG}</td><td>- 55 to +150</td><td>°C</td></tr></table>				Parameter	Symbol	Limit	Unit	Drain-Source Voltage	V_{DS}	- 20V	V	Gate-Source Voltage	V_{GS}	± 8	V	Continuous Drain Current	I_D	- 2.3	A	Pulsed Drain Current	I_{DM}	- 10	A	Maximum Power Dissipation	Ta = 25 °C	P_D	1.25	W	Ta = 75 °C		0.8	Operating Junction Temperature	T_J	+150	°C	Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to +150	°C
Parameter	Symbol	Limit	Unit																																				
Drain-Source Voltage	V_{DS}	- 20V	V																																				
Gate-Source Voltage	V_{GS}	± 8	V																																				
Continuous Drain Current	I_D	- 2.3	A																																				
Pulsed Drain Current	I_{DM}	- 10	A																																				
Maximum Power Dissipation	Ta = 25 °C	P_D	1.25	W																																			
	Ta = 75 °C		0.8																																				
Operating Junction Temperature	T_J	+150	°C																																				
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to +150	°C																																				
Thermal Performance <table><tr><th>Parameter</th><th>Symbol</th><th>Limit</th><th>Unit</th></tr><tr><td>Lead Temperature (1/8" from case)</td><td>T_L</td><td>5</td><td>S</td></tr><tr><td>Junction to Ambient Thermal Resistance (PCB mounted)</td><td>$R\theta_{ja}$</td><td>100</td><td>°C/W</td></tr></table>				Parameter	Symbol	Limit	Unit	Lead Temperature (1/8" from case)	T_L	5	S	Junction to Ambient Thermal Resistance (PCB mounted)	$R\theta_{ja}$	100	°C/W																								
Parameter	Symbol	Limit	Unit																																				
Lead Temperature (1/8" from case)	T_L	5	S																																				
Junction to Ambient Thermal Resistance (PCB mounted)	$R\theta_{ja}$	100	°C/W																																				

Note: Surface mounted on FR4 board $t \leq 5\text{sec}$.

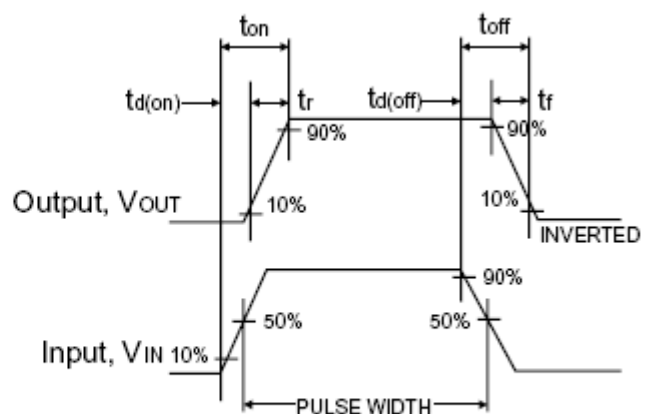


Electrical Characteristics						
Ta = 25 °C, unless otherwise noted						
Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = - 250uA	BV _{DSS}	- 20	--	--	V
Drain-Source On-State Resistance	V _{GS} = - 4.5V, I _D = -2.8A	R _{DS(ON)}	--	95	130	mΩ
Drain-Source On-State Resistance	V _{GS} = - 2.5V, I _D = -2.0A	R _{DS(ON)}	--	122	190	
Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = - 250uA	V _{GS(TH)}	- 0.45	--	--	V
Zero Gate Voltage Drain Current	V _{DS} = - 16V, V _{GS} = 0V	I _{DSS}	--	--	- 1.0	uA
Gate Body Leakage	V _{GS} = ± 8V, V _{DS} = 0V	I _{GSS}	--	--	± 100	nA
On-State Drain Current	V _{DS} ≥ - 10V, V _{GS} = -5V	I _{D(ON)}	- 6	--	--	A
Forward Transconductance	V _{DS} = - 5V, I _D = - 2.8A	g _{fs}	--	6.5	--	S
Dynamic						
Total Gate Charge	V _{DS} = - 6V, I _D = - 2.8A, V _{GS} = - 4.5V	Q _g	--	5.4	10	nC
Gate-Source Charge		Q _{gs}	--	0.8	--	
Gate-Drain Charge		Q _{gd}	--	1.1	--	
Turn-On Delay Time	V _{DD} = - 6V, R _L = 6Ω, I _D = - 1A, V _{GEN} = - 4.5V, R _G = 6Ω	t _{d(on)}	--	5	25	nS
Turn-On Rise Time		t _r	--	19	60	
Turn-Off Delay Time		t _{d(off)}	--	95	110	
Turn-Off Fall Time		t _f	--	65	80	
Input Capacitance	V _{DS} = - 6V, V _{GS} = 0V, f = 1.0MHz	C _{iss}	--	447	--	pF
Output Capacitance		C _{oss}	--	127	--	
Reverse Transfer Capacitance		C _{rss}	--	80	--	
Source-Drain Diode						
Max. Diode Forward Current		I _S	--	--	- 1.6	A
Diode Forward Voltage	I _S = - 1.6A, V _{GS} = 0V	V _{SD}	--	- 0.8	- 1.2	V

Note : pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$



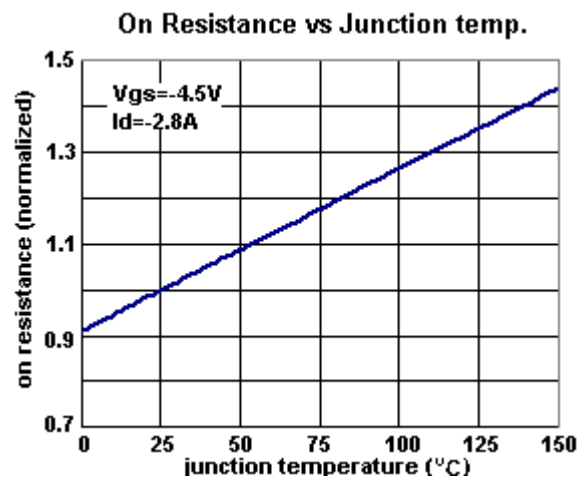
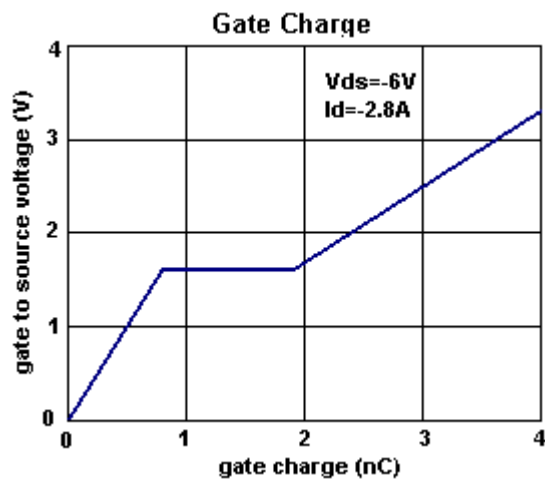
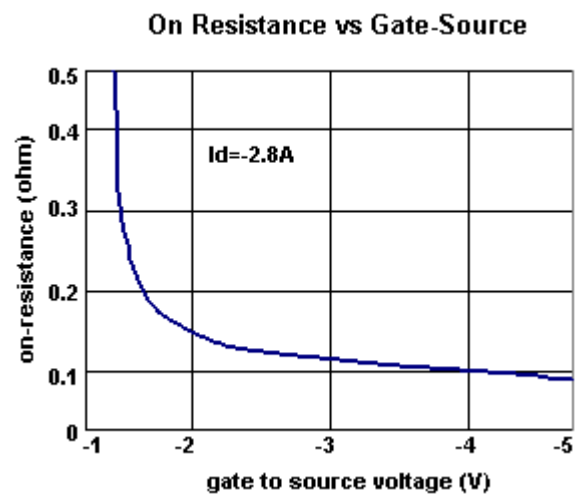
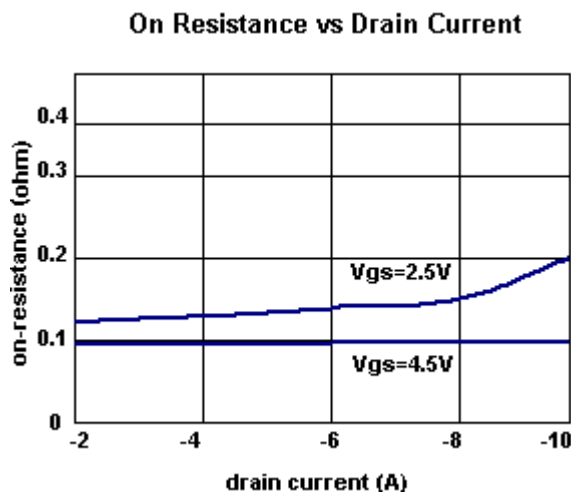
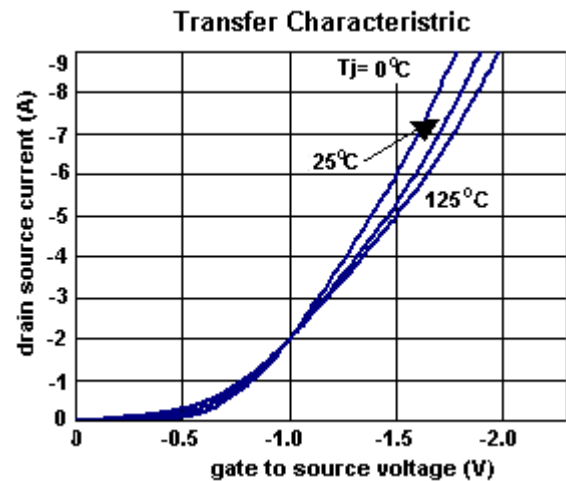
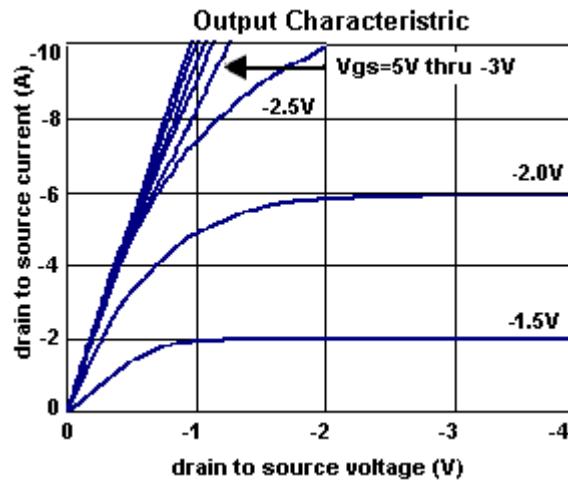
Switching Test Circuit



Switchin Waveforms

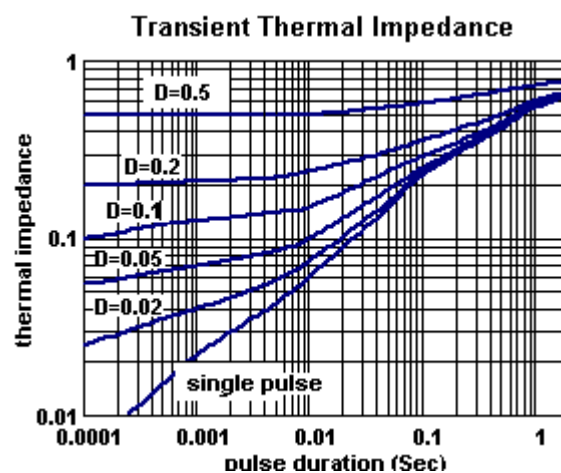
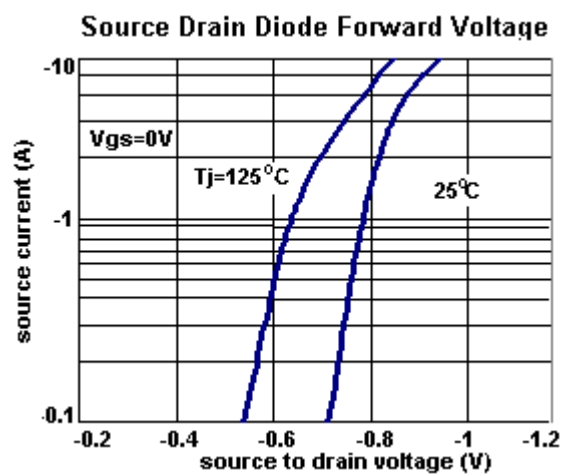


Typical Characteristics Curve (Ta = 25 °C unless otherwise noted)

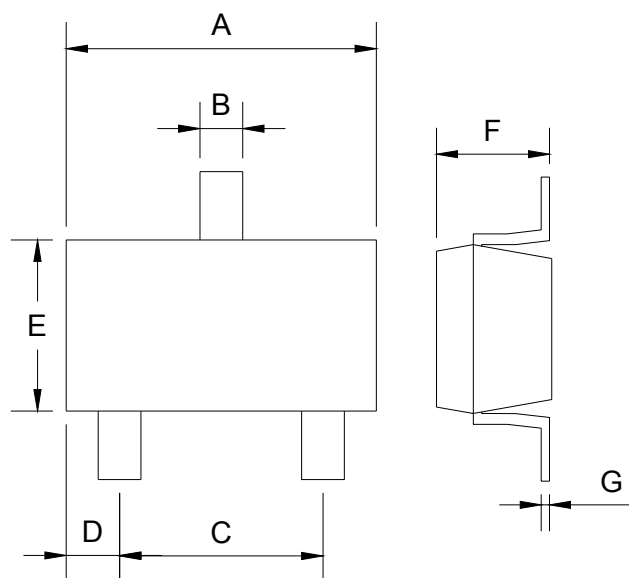




Typical Characteristics Curve (Ta = 25 °C unless otherwise noted)



SOT-23 Mechanical Drawing



SOT-23 DIMENSION				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.88	2.91	0.113	0.115
B	0.39	0.42	0.015	0.017
C	1.78	2.03	0.070	0.080
D	0.51	0.61	0.020	0.024
E	1.59	1.66	0.063	0.065
F	1.04	1.08	0.041	0.043
G	0.07	0.09	0.003	0.004